



# VACUUM APPLICATOR VA 730/N





## DESCRIPTION

The Vacuum Applicator VA 730/N is a semi-automatic machine, designed and built to ensure complete elimination of air from the surfaces of a printed circuit board, as well as perfect encapsulation of the traces. The machine has been developed for simultaneous application on both sides of the printed circuit panel of dry film, high conformation dry film solder mask ConforMASK™, and conventional dry film solder mask, or dielectric film and copper foil for SBU technology. In order to obtain perfect adhesion of the dry film and ensure total lack of air bubbles, VA 730/N employs heat, vacuum and pressure lamination.

## ADVANTAGES

- Suitable for innerlayer or rigid panels full range from 0.05–6.40 mm (0.002–0.025 in.) thickness
- Panel sizes up to 787 x 787 mm (31 x 31 in.)
- Entire platen area can be filled with one or more panels
- State-of-the-art vacuum technology
- Completely controlled by PLC—operator interface in local language
- Platen temperatures individually controlled
- Suitable for clean room operations
- Convenient operator access
- Greatly reduces solder mask film waste

<b>Overall Dimensions</b>		<b>Panel Size</b>	
Width	1,320 mm (52.0 in.)	Width (max.)	787 mm (31.0 in.)
Length	2,390 mm (94.1 in.)	Length (max.)	787 mm (31.0 in.)
Height (min.–max.)	1,310–1,470 mm (51.6–57.9 in.)	Thickness (min.–max.)	0.05–6.4 mm (0.002–0.252 in.)
<b>Electrical Requirements</b>		<b>Working Height (Adjustment)</b>	
Power Type	3 phase; 50/60 Hz + Ground	Height (min.–max.)	960–1,040 mm (37.8–40.9 in.)
Power Consumption	8.0 KVA		
Nominal Voltage*	400/480/220/200V ±7%		
<b>Compressed Air</b>			
Consumption	7 NI/cycle (0.25 cfm)		
Working Pressure (max.)	6 kg/cm (85.3 psi)		
<b>Weight</b>			
Gross	1,257 kg (2,770 lbs.)		
Net	985 kg (2,171 lbs.)		
*Different voltage can be provided upon requirement.			